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AMAT/7385/CMP/ECP/RKK

ATTY DKT. NO.: U.S. SERIAL NO.: FILED: APPLICANT: TITLE: UNKNOWN HEREWITH

APPLIED MATERIALS, INC.

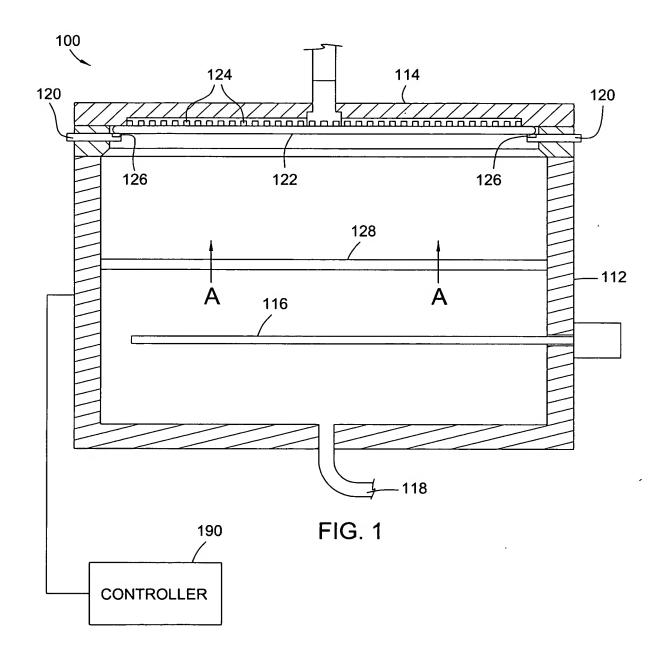
HOMOGENEOUS COPPER-PALLADIUM ALLOY PLATING FOR ENHANCEMENT OF ELECTRO-MIGRATION RESISTANCE IN INTERCONNECTS

INVENTOR: PADHI, ET AL.

EXPRESS MAIL NO.: EV349851973US

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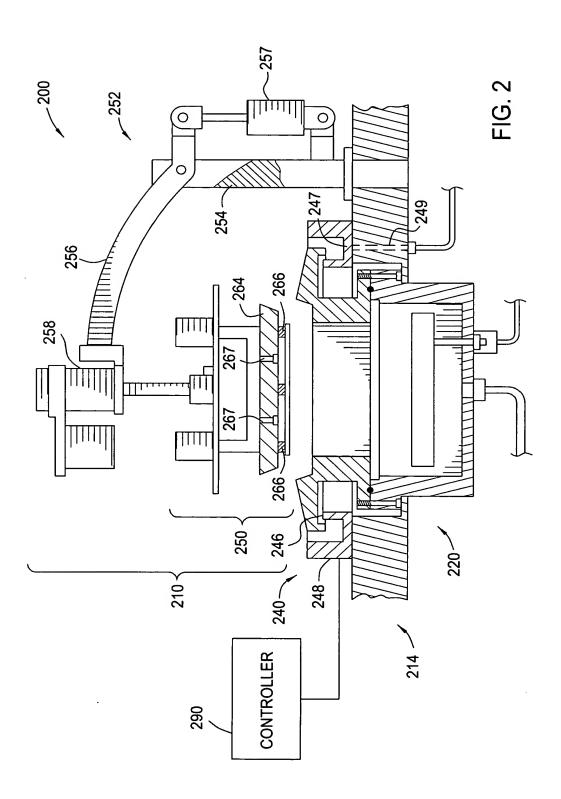
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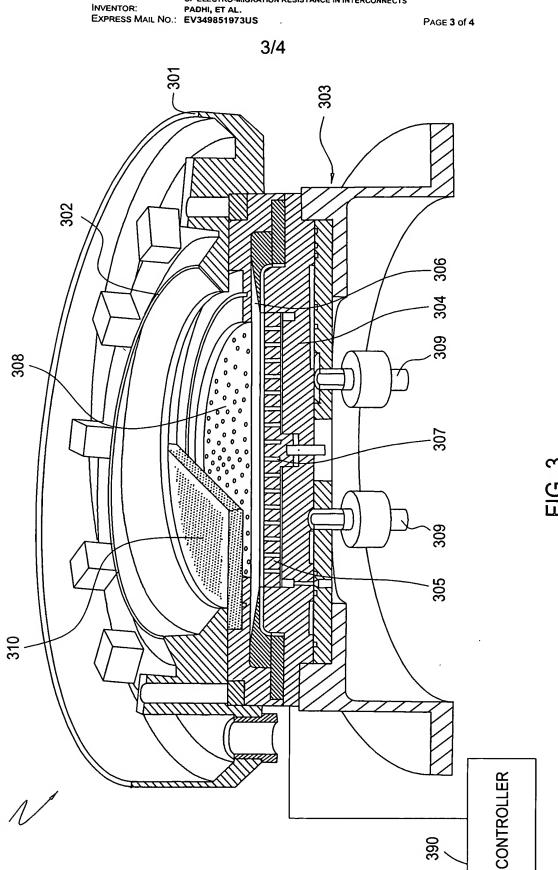
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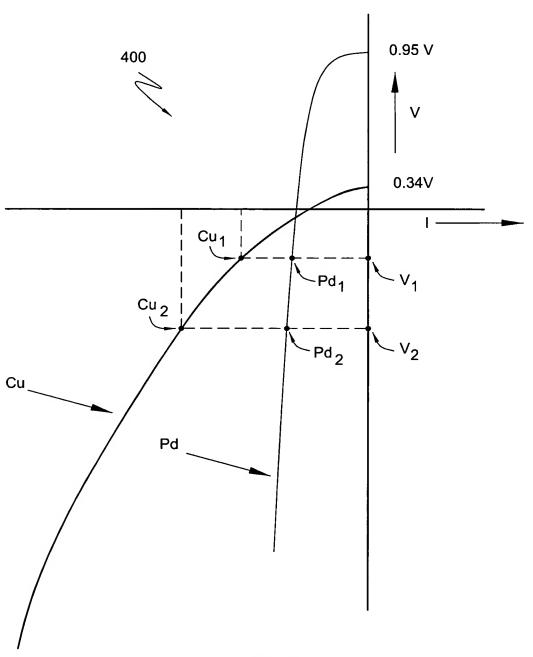


FIG. 4

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